

ABSTRACT

A circuit board according to the invention is made from two or more laminates each made of a fusible dielectric material, which laminates are bonded to each other along respective inner faces thereof. Each such laminate is preferably a pre-preg sheet containing both a heat-fusible resin and a reinforcing fiber filler to provide the desired stiffness and strength. A number of first electrical contacts are exposed on an outer face of the first laminate, and second electrical contacts are exposed on an outer face of the second laminate. The circuit board further includes a plurality of electrical conductors each running from a first contact to a second contact, the conductors including elongated conductive lines extending along one of the first or second laminates, and vias extending through the first and second laminates which have been filled with an electrically conductive via filler.

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